



PK602 (v1.0) March 15, 2013

100% Material Declaration Data Sheet for Artix-7 FBG484 Package

Average Weight: 2.1115 g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.237267	11.237
	Silicon	7440-21-3	100.00		0.237267	
Solder Bump					0.011261	0.533
	Tin	7440-31-5	63.00		0.007094	
	Lead	7439-92-1	37.00		0.004167	
Underfill					0.030000	1.421
	Bisphenol F/ epichlorohydrin copolymer	9003-36-5	20.00		0.006000	
	Phenolic resin	Trade Secret	15.00		0.004500	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.00		0.001500	
	Amine type accelerator	Trade Secret	5.00		0.001500	
	Silicon dioxide	60676-86-0	51.50		0.015450	
	Carbon black	1333-86-4	1.00		0.000300	
	Additives	Trade Secret	2.50		0.000750	
Solder Ball					0.404317	19.148
	Tin	7440-31-5	96.50		0.390166	
	Silver	7440-22-4	3.00		0.012130	
	Copper	7440-50-8	0.50		0.002022	
Substrate					1.428702	67.661
	Copper	7440-50-8	36.85		0.526477	
	Tin	7440-31-5	1.07		0.015287	
	Lead	7439-92-1	0.26		0.003715	
	Silver	7440-22-4	0.02		0.000286	
	BT Core	Trade Secret	48.20		0.688634	
	ABF	Trade Secret	11.12		0.158872	
	SolderMask	Trade Secret	2.48		0.035432	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/15/2013	1.0	Xilinx Initial Release

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